



SEMiX® 3s

SEMiX303GB12Vs

Features

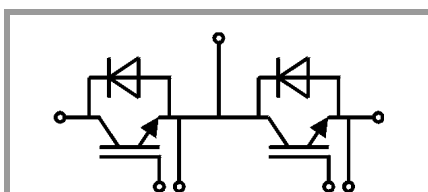
- Homogeneous Si
- $V_{CE(sat)}$ with positive temperature coefficient
- High short circuit capability
- UL recognised file no. E63532

Typical Applications*

- AC inverter drives
- UPS
- Electronic Welding

Remarks

- Case temperature limited to $T_C=125^\circ\text{C}$ max.
- Product reliability results are valid for $T_J=150^\circ\text{C}$
- Dynamic values apply to the following combination of resistors:
 $R_{Gon,main} = 1,0 \Omega$
 $R_{Goff,main} = 1,0 \Omega$
 $R_{G,X} = 2,2 \Omega$
 $R_{E,X} = 1,0 \Omega$



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Absolute Maximum Ratings				
Symbol	Conditions		Values	Unit
IGBT				
V _{CES}	T _j = 25 °C		1200	V
I _C	T _j = 175 °C	T _c = 25 °C	448	A
		T _c = 80 °C	342	A
I _{Cnom}			300	A
I _{CRM}	I _{CRM} = 3xI _{Cnom}		900	A
V _{GES}			-20 ... 20	V
t _{psc}	V _{CC} = 720 V V _{GE} ≤ 15 V V _{CES} ≤ 1200 V	T _j = 125 °C	10	μs
T _j			-40 ... 175	°C
Inverse diode				
I _F	T _j = 175 °C	T _c = 25 °C	327	A
		T _c = 80 °C	244	A
I _{Fnom}			300	A
I _{FRM}	I _{FRM} = 3xI _{Fnom}		900	A
I _{FSM}	t _p = 10 ms, sin 180°, T _j = 25 °C		1485	A
T _j			-40 ... 175	°C
Module				
I _{t(RMS)}	T _{terminal} = 80 °C		600	A
T _{stg}			-40 ... 125	°C
V _{isol}	AC sinus 50Hz, t = 1 min		4000	V

Characteristics						
Symbol	Conditions		min.	typ.	max.	Unit
IGBT						
V _{CE(sat)}	I _C = 300 A	T _j = 25 °C		1.75	2.2	V
	V _{GE} = 15 V chipelevel	T _j = 150 °C		2.2	2.5	V
V _{CE0}		T _j = 25 °C		0.94	1.04	V
		T _j = 150 °C		0.88	0.98	V
r _{CE}	V _{GE} = 15 V	T _j = 25 °C		2.7	3.9	mΩ
		T _j = 150 °C		4.4	5.1	mΩ
V _{GE(th)}	V _{GE} =V _{CE} , I _C = 12 mA		5.5	6	6.5	V
I _{CES}	V _{GE} = 0 V	T _j = 25 °C		0.1	0.3	mA
	V _{CE} = 1200 V	T _j = 150 °C				mA
C _{ies}	V _{CE} = 25 V V _{GE} = 0 V	f = 1 MHz		18.0		nF
C _{oes}		f = 1 MHz		1.77		nF
C _{res}		f = 1 MHz		1.77		nF
Q _G	V _{GE} = - 8 V...+ 15 V			3300		nC
R _{Gint}	T _j = 25 °C			2.50		Ω
t _{d(on)}	V _{CC} = 600 V	T _j = 150 °C		470		ns
t _r	I _C = 300 A	T _j = 150 °C		72		ns
E _{on}	V _{GE} = ±15 V	T _j = 150 °C		26.5		mJ
t _{d(off)}	R _{G on} = 2.1 Ω	T _j = 150 °C		665		ns
t _f	R _{G off} = 2.1 Ω	T _j = 150 °C		109		ns
E _{off}	di/dt _{on} = 4200 A/μs di/dt _{off} = 2600 A/μs du/dt _{off} = 6600 V/μs	T _j = 150 °C		36.3		mJ
R _{th(j-c)}	per IGBT				0.1	K/W



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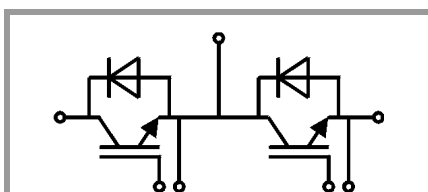
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Characteristics						
Symbol	Conditions		min.	typ.	max.	Unit
Inverse diode						
V _F = V _{EC}	I _F = 300 A V _{GE} = 0 V chip	T _J = 25 °C		2.2	2.52	V
		T _J = 150 °C		2.2	2.5	V
V _{F0}		T _J = 25 °C	1.1	1.3	1.5	V
		T _J = 150 °C	0.7	0.9	1.1	V
r _F		T _J = 25 °C	2.7	3.0	3.4	mΩ
		T _J = 150 °C	3.5	4.2	4.6	mΩ
I _{RRM}	I _F = 300 A di/dt _{off} = 4600 A/μs V _{GE} = -15 V V _{CC} = 600 V	T _J = 150 °C		283		A
Q _{rr}		T _J = 150 °C		52		μC
E _{rr}		T _J = 150 °C		21.4		mJ
R _{th(j-c)}		per diode			0.19	K/W
Module						
L _{CE}				20		nH
R _{CC'+EE'}	res., terminal-chip	T _C = 25 °C		0.7		mΩ
		T _C = 125 °C		1		mΩ
R _{th(c-s)}	per module			0.04		K/W
M _s	to heat sink (M5)		3		5	Nm
M _t		to terminals (M6)	2.5		5	Nm
						Nm
w					300	g
Temperatur Sensor						
R ₁₀₀	T _C =100°C (R ₂₅ =5 kΩ)			493 ± 5%		Ω
B _{100/125}	R _(T) =R ₁₀₀ exp[B _{100/125} (1/T-1/T ₁₀₀)]; T[K];			3550 ±2%		K



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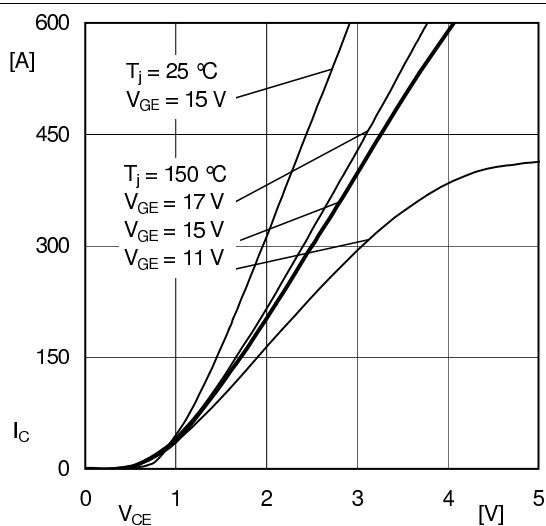


Fig. 1: Typ. output characteristic, inclusive $R_{CC'} + E_{E'}$

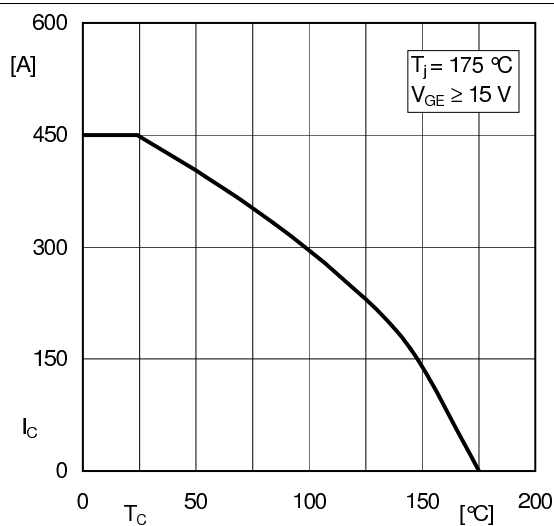


Fig. 2: Rated current vs. temperature $I_C = f(T_C)$

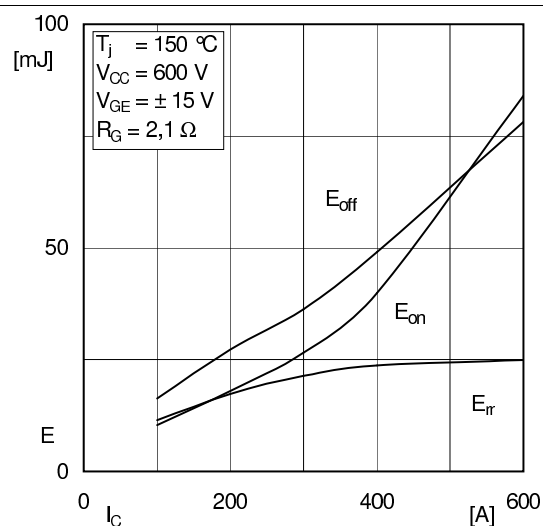


Fig. 3: Typ. turn-on /-off energy = $f(I_C)$

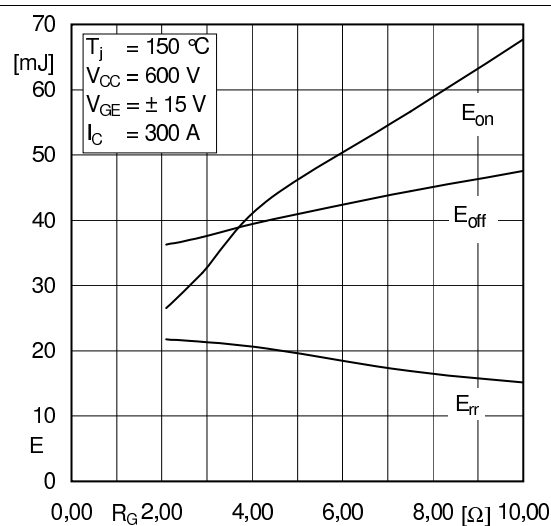


Fig. 4: Typ. turn-on /-off energy = $f(R_G)$

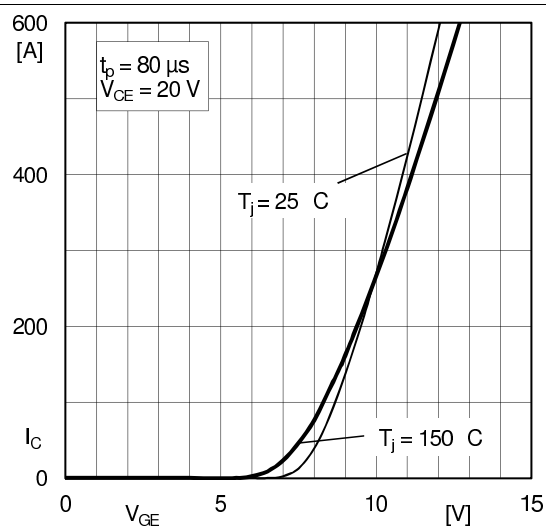


Fig. 5: Typ. transfer characteristic

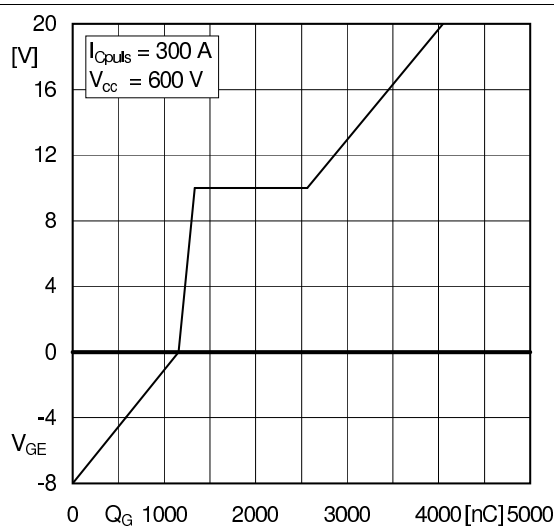


Fig. 6: Typ. gate charge characteristic

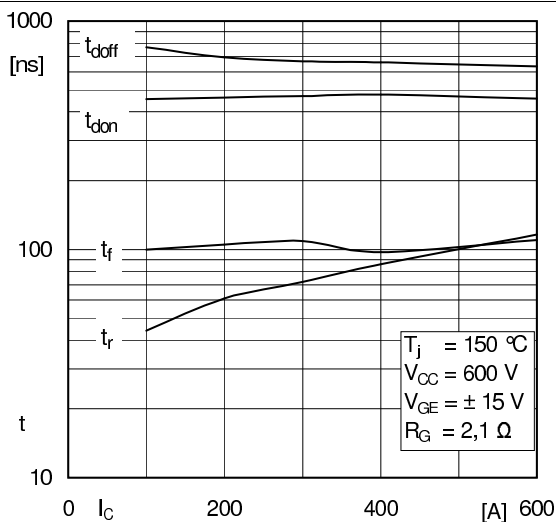


Fig. 7: Typ. switching times vs. I_C

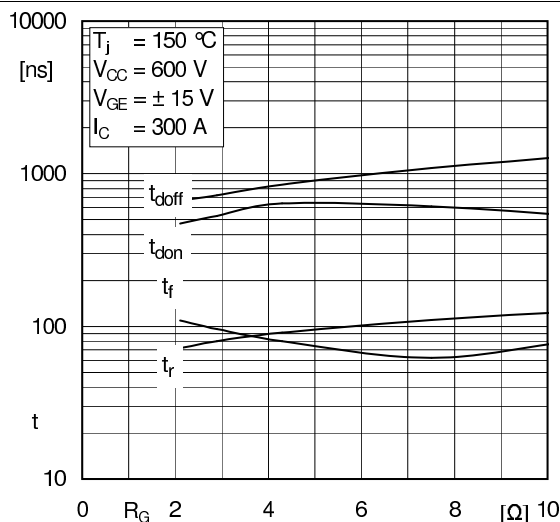


Fig. 8: Typ. switching times vs. gate resistor R_G

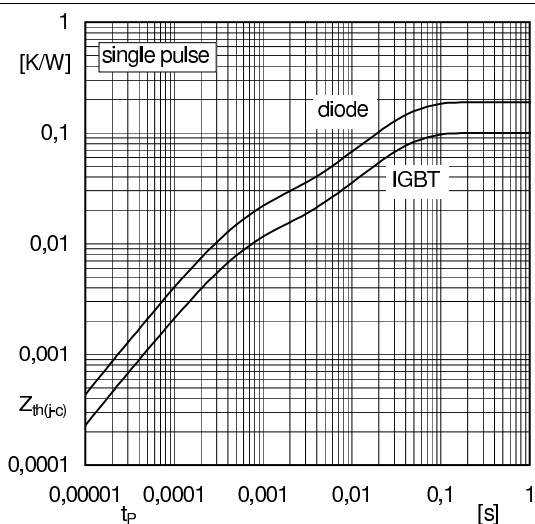


Fig. 9: Typ. transient thermal impedance

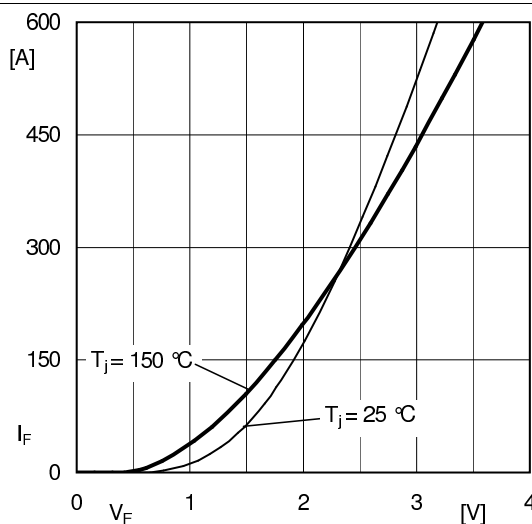


Fig. 10: Typ. CAL diode forward charact., incl. $R_{CC'+EE'}$

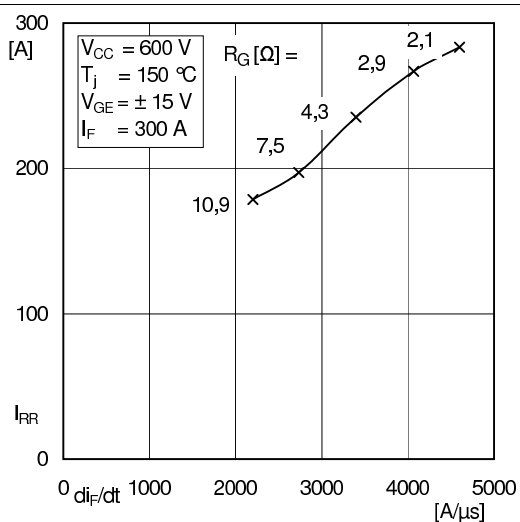


Fig. 11: Typ. CAL diode peak reverse recovery current

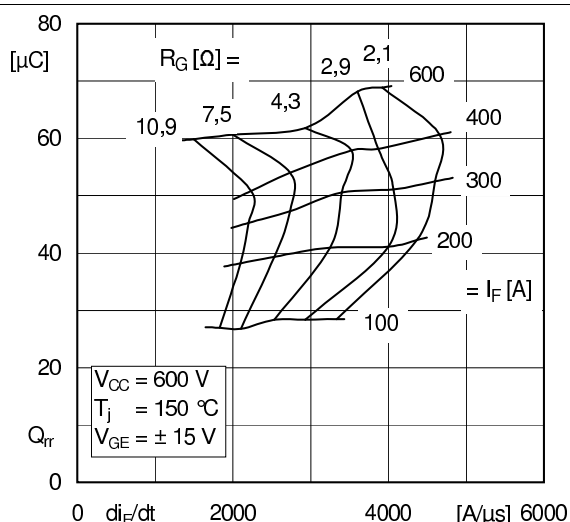
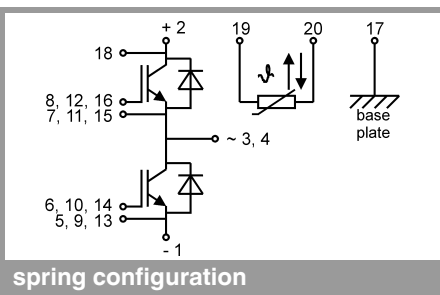


Fig. 12: Typ. CAL diode recovery charge



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